Ceramic Quad Flatpack (CQFP)



84 LEAD CERAMIC QUAD FLATPACK PACKAGE

| | INCHES | | MILLIMETERS | | |
|--------|-----------|--------|-------------|-------|-------|
| SYMBOL | MIN | MAX | MIN | MAX | NOTES |
| A | - | 0.105 | - | 2.67 | - |
| b | 0.015 | 0.022 | 0.38 | 0.56 | 2 |
| b1 | 0.015 | 0.019 | 0.38 | 0.48 | 2 |
| С | 0.008 | 0.015 | 0.20 | 0.38 | 2 |
| c1 | 0.008 | 0.012 | 0.20 | 0.30 | 2 |
| D | 1.800 | 2.000 | 45.72 | 50.80 | - |
| E | 1.800 | 2.000 | 45.72 | 50.80 | - |
| D1 | 1.135 | 1.170 | 28.83 | 29.72 | - |
| E1 | 1.135 | 1.170 | 28.83 | 29.72 | - |
| е | 0.050 BSC | | 1.27 BSC | | - |
| e1 | 0.012 | - | 0.30 | - | 4 |
| e2 | 0.012 | - | 0.30 | - | - |
| L | 0.320 | 0.450 | 8.13 | 11.43 | - |
| Q | 0.070 | 0.090 | 1.78 | 2.29 | 6 |
| М | - | 0.0015 | - | 0.04 | 2 |
| Ν | 84 | | 84 | | 3 |

NOTES:

1. Index area: A notch or a pin one identification mark shall be located adjacent to pin one and shall be located within the shaded area shown. The manufacturer's identification shall not be used as a pin one identification mark.

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- 2. Dimensions b1 and c1 apply to lead base metal only. Dimension M applies to lead plating and finish thickness. The maximum limits of lead dimensions b and c or M shall be measured at the centroid of the finished lead surfaces, when solder dip or tin plate lead finish is applied.
- 3. N is the maximum number of terminal positions.
- 4. Measure dimension e1 at all four corners.
- 5. For bottom-brazed lead packages, no organic or polymeric materials shall be molded to the bottom of the package to cover the leads.
- 6. Dimension Q shall be measured at the point of exit (beyond the meniscus) of the lead from the body. Dimension Q minimum shall be reduced by 0.0015 inch (0.038mm) maximum-when solder dip lead finish is applied.
- 7. Dimensioning and tolerancing per ANSI Y14.5M 1982.
- 8. Controlling dimension: Inch.